A cleaning agent for a semiconductor device contains a hydroxide, water and a compound expressed in the following general formula (I) and/or the following general formula (II):

$$HO-((EO)_x-(PO)_y)_z-H$$

(I)

$$R-[(EO)_x-(PO)_y)_z-H]_m$$

(II)

Thus provided is a cleaning agent for a semiconductor device, which is so improved as not to disconnect a wire or an embedded conductive layer.

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